

Final Product Change Notification

202112006F02: Additional Wafer Source for SE05x, A5000 and Related Products

Note: This notice is NXP Company Proprietary.

Issue Date: Oct 02, 2022 Effective date: Dec 31, 2022

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Management summary

NXP is making an additional wafer foundry available for the CMOS040 technology used to manufacture wafers for SE05x products, as well as J3R and A5000 products. For orders after the change, NXP planners can source material from one of two possible foundries. The commercial type naming scheme is adapted to make this dual-sourcing possible without changes to existing customer ordering type names or 12NCs (ordering codes).

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[X]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrica spec./Test coverage
[]Firmware	[]Other			

PCN Overview Description

Besides the existing source for wafers, a second source will become available after the change. This is Globalfoundries fab 1 in Dresden, Germany (GF1). This foundry will produce products with the same form, fit and function as the existing source (Globalfoundries fab 7 in Singapore, GF7). GF1 has the same quality and security certifications like GF7. NXP has performed an extensive qualification process to ensure wafer supplies are equivalent from both sources in all observable aspects.

To help our customers execute future orders in a more flexible way, the type naming scheme for affected parts is changing. There is a change in the coding for the letter that identifies wafer source. The letter "z", which previously had the meaning "wafer source GF7" will have the meaning "wafer source GF1 or GF7" after the change. Individual customer orders will typically be fulfilled only from one single source each, not from a mixture of both sources.

Reason

NXP strives to provide larger flexibility to customers and our production fulfilment. Being able to source wafers for EdgeLock SE05x, J3R and A5000 products from more than one source will

provide a more resilient supply situation. In the light of the global semiconductor supply broadly discussed in public media, we believe this change will be helpful.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from Oct 03, 2022

Production

Planned first shipment Oct 17, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

"old products" does not apply, as GF7 will still remain a valid wafer production source also after the change.

Additional information

Self qualification: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 01, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Appendix A: Changed Products

PCN#: FPCN22966XV Issue Date: Sep 29, 2022

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FGH75T65SQDNL4		AFGHL75T65SQDT	NA	
FGH75T65SQD-F155		AFGHL75T65SQDT	NA	
FGH40T65SQD-F155		AFGHL75T65SQDT	NA	
FGHL50T65SQDT		AFGHL75T65SQDT	NA	
NXH80T120L3Q0S3G		SNXH100M65L4Q2F2P2G	NA	
FGH75T65SQDT-F155		AFGHL75T65SQDT	NA	